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(12)

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(43)

10-2005-0011393
2005 01 29

(21) 10-2003-0050484
(22) 2003 07 23

(71) 416

(72) 105 1406

13-4

109 306

102 1102

(74)

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(54)

가
;
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2

, , ,

1

2

3 4 2 가

5 6

(bonding pads) (chip) 가

(customer needs)

BOC

MCP

(crossing)

가

가

가

가

가

1

(PD1-PD6)

PD1-PD6)

(PD1-PD6)

(W1-W5)
(W11-W51,W61)

1

(L10-
(L20-

L14)

L25)

L20-L25)

(PD1-PD6)

1

2

(PD1-PD6)

(200)

2

2

(200)

가

1

(100)

(PD1-PD5)

(W1-W5)

(W5)

(L10-L14)

2

가
(L20-L2

5)

(W1)

(W2)

가

가 .

(customer needs)

가
가

(aspect)

2가

가
가

(note)

가

2

1

(PD1-PD7)

(PD1-PD7)

(PD1-PD7)

(W1-W5)

1

(L10-L14)

(W11-W16)

2

(L20-L25)

2

(PD1-PD6)

2

(L20-L25)

2

(210)

(PD1-PD6)

2

(210)

1

(110)

(W3,W2,W1)

1

가

(PD4,PD6,PD7)

1

2 (200) (B) (210) (B) (PD4)가 1 (100) (B1) 2 (C1)
 2 (PD4)가 1 (110) (PD4)
 , 2 (210) , 2 (110)
 , 1 (110)

2 가 가

3 4

3 4 2 가 (2)가 (8) (10) (6)
 가 3 (2) (20)

4 가 3 (2) (2)가 (6) (20) (10)

3 4 (8) (6) TSOP BGA

, 3 4 , 2 가

5 6 (PD1)

(PD4) (PD5), (PD4) (PD7) (PD2)

, 3 4 가 가 가

, 가 , 가 , 가

(57)

1. 가 ;

;

1 2.

2 3.

3 4. 2가

2 5.

1 6. 가 1 가
2

7. ;
;
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7 8.

7 9.

7 10.

11. ;

;
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;

11 12. ,

11 13. ,

11 14. ,

15.

:

1 ;
2 가 ,
가

1 2

15 16. , TSOP

15 17. , BGA

18.

:

1 ;
2 가 ,

1 2

가

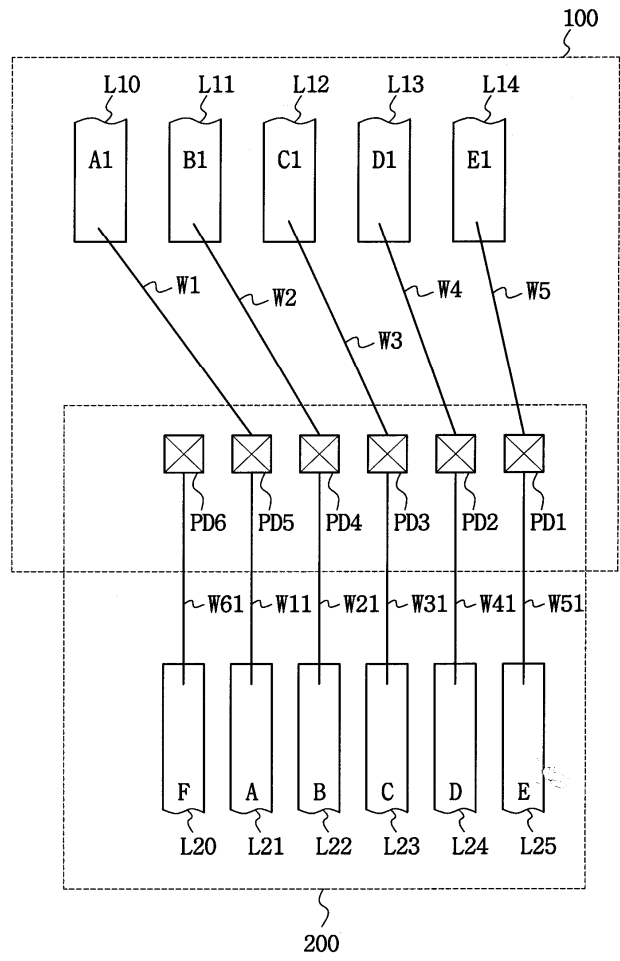
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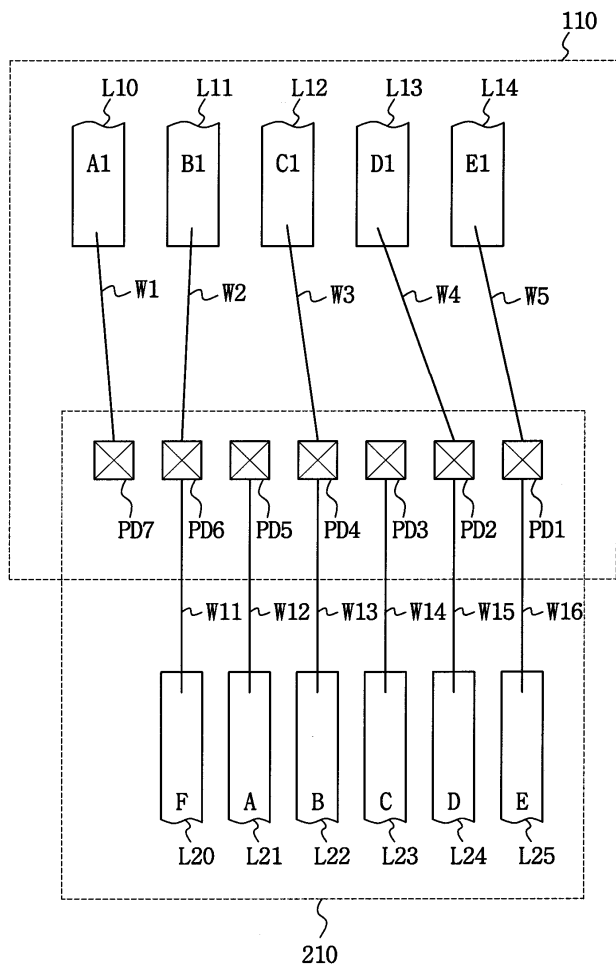
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20.

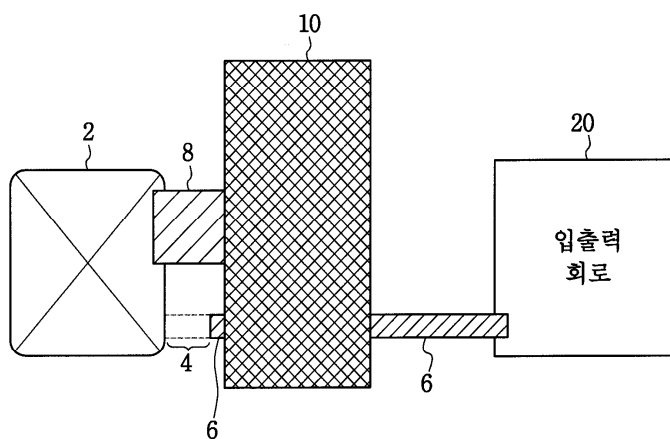
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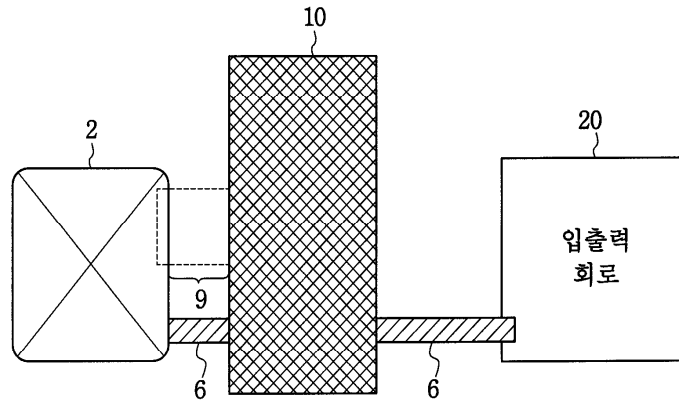
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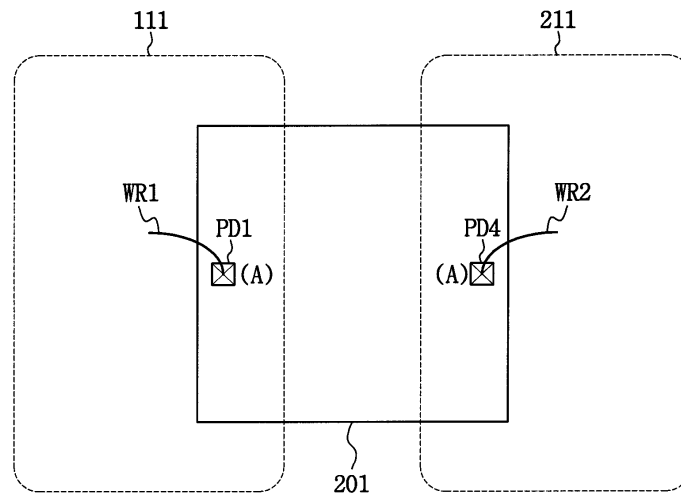
3



4



5



6

